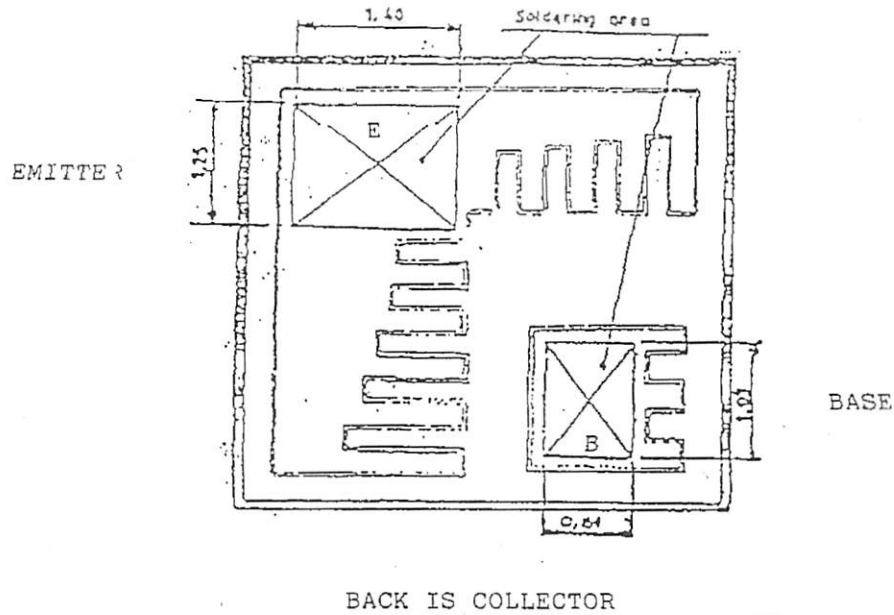




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Topside Metal: Al (Aluminum)

Backside:

Backside Potential: Collector

Mask Ref:

Bond Pads (Mils):

APPROVED BY:

MFG: Phillips

DIE SIZE (Mils): 153 X 153

THICKNESS:

DATE: 3/3/00

P/N: BDX65

DG 10.1.2
Rev A 3-4-99